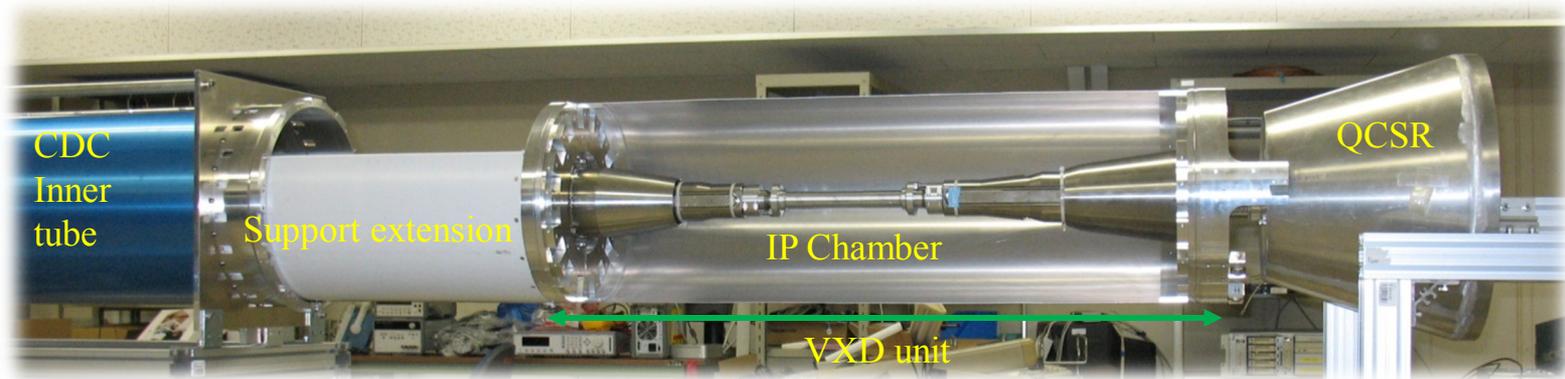


Construction of the Interaction Region



The 18th KEKB Accelerator Review Committee

KEK, 4-6 March 2013

K. Kanazawa

for

KEKB Vacuum Group

IR Technical Meeting Member

IR Installation Meeting Member

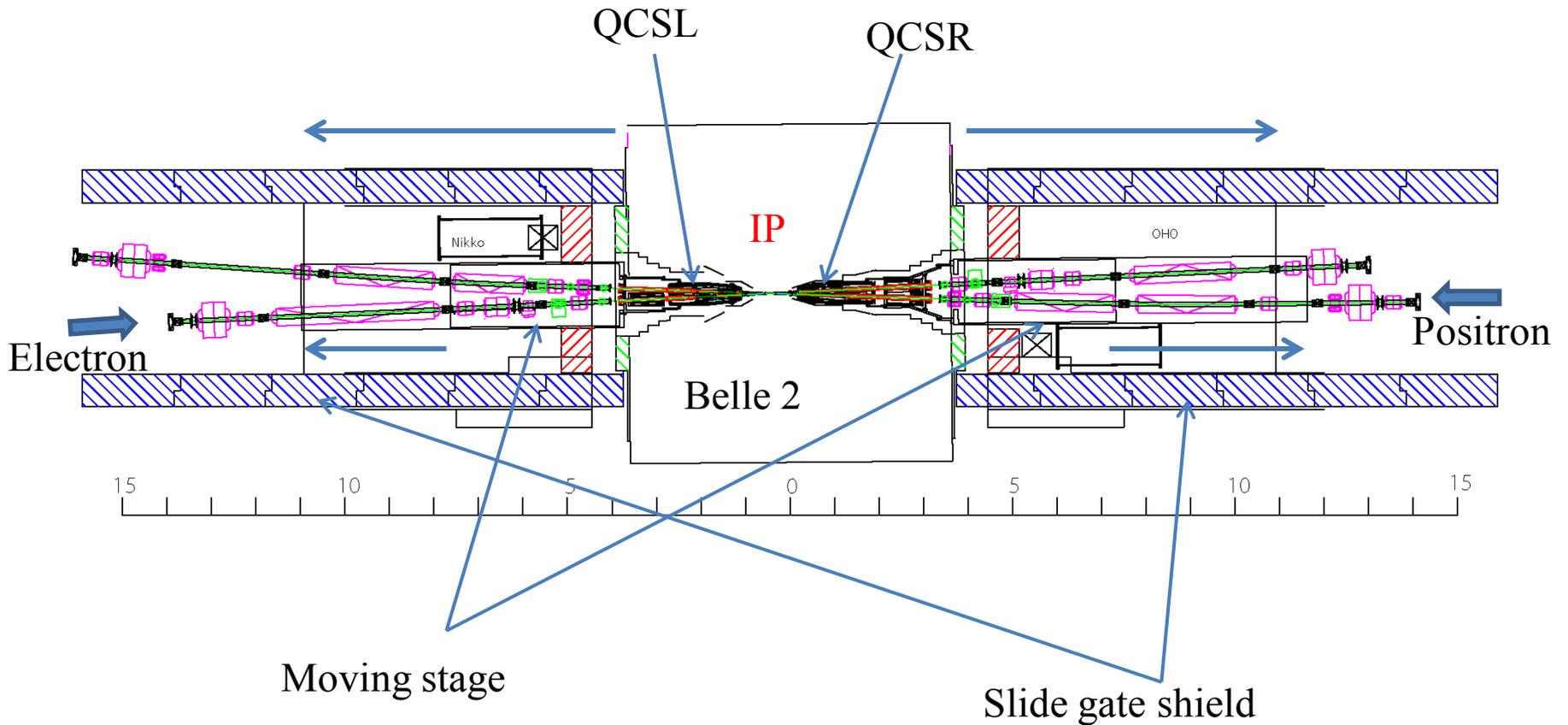
SVD/IR Mechanics Meeting Member



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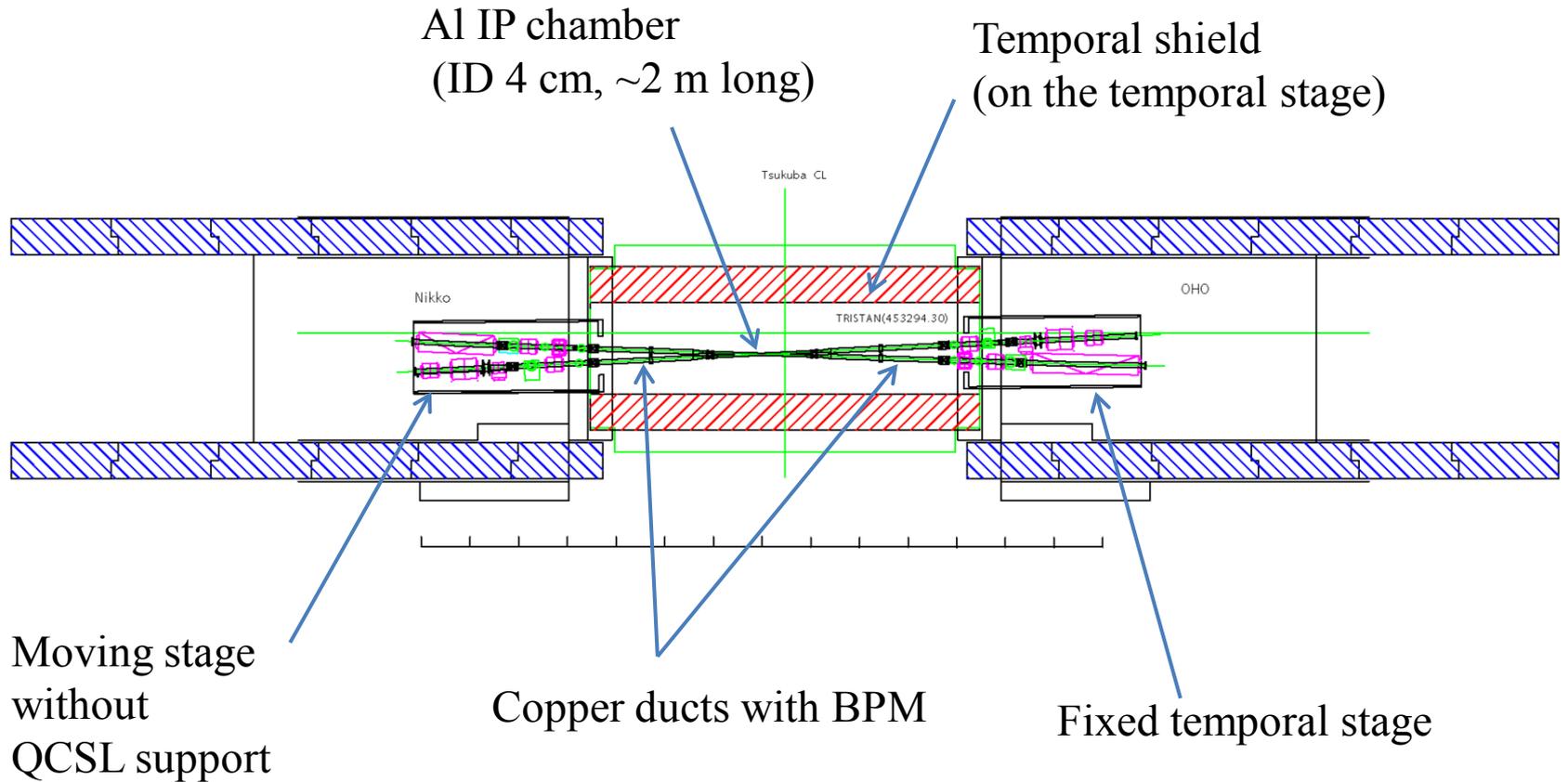
- Sketch of the interaction region
- Mile-stones and task schedule
- Bridge reinforcement
- Installation scenario
- Vacuum around IR
- IP chamber
- Radiation shield
- Summary

Sketch of the Interaction Region Phase 2

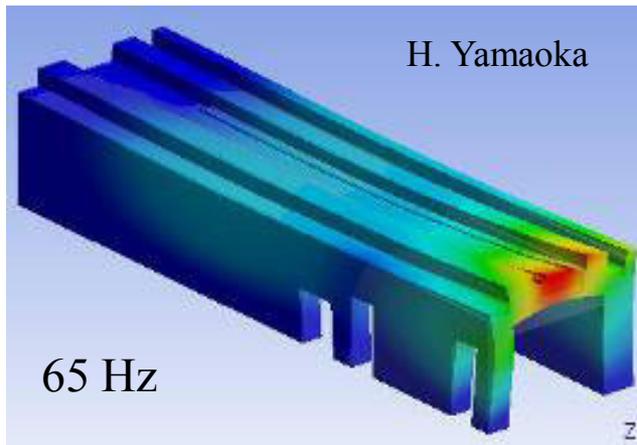


Sketch of the Interaction Region

Phase 1



Bridge Reinforcement



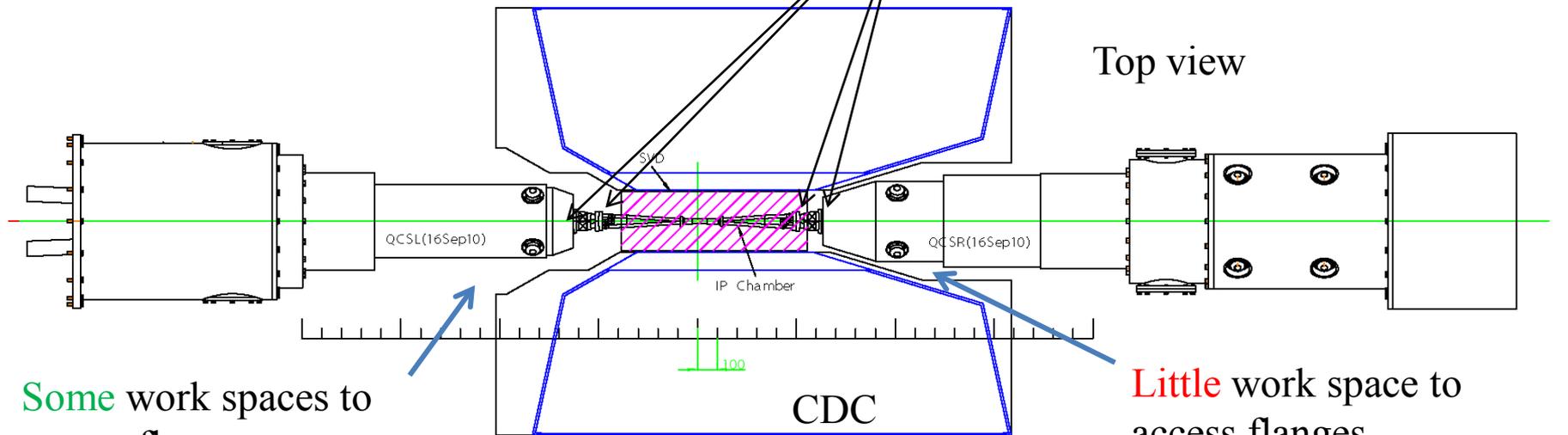
- The end of the bridge where QCS lies on is mechanically weak. For example the vertical oscillation of the place with 65 Hz is one of the lowest modes of the bridge oscillation.
- The measured amplitudes during KEKB are tolerable if QC1E and QC1P oscillate with the same phase (this is the most probable case).
- However, if a simple and effective way of reinforcement of this part is available, it should be done.
- The chance of the work is quite limited. The decision should be done as soon as possible.

Installation Scenario

Basic conditions

- IP chamber is supported by VXD frame.
Both sides of IP chamber are fixed to the VXD frame transversally and are free longitudinally.
- VXD is supported by CDC.
The R-side of VXD is aligned transversally and is free longitudinally.
The L-side of VXD is fixed to CDC.
- QCS cryostats can move out.

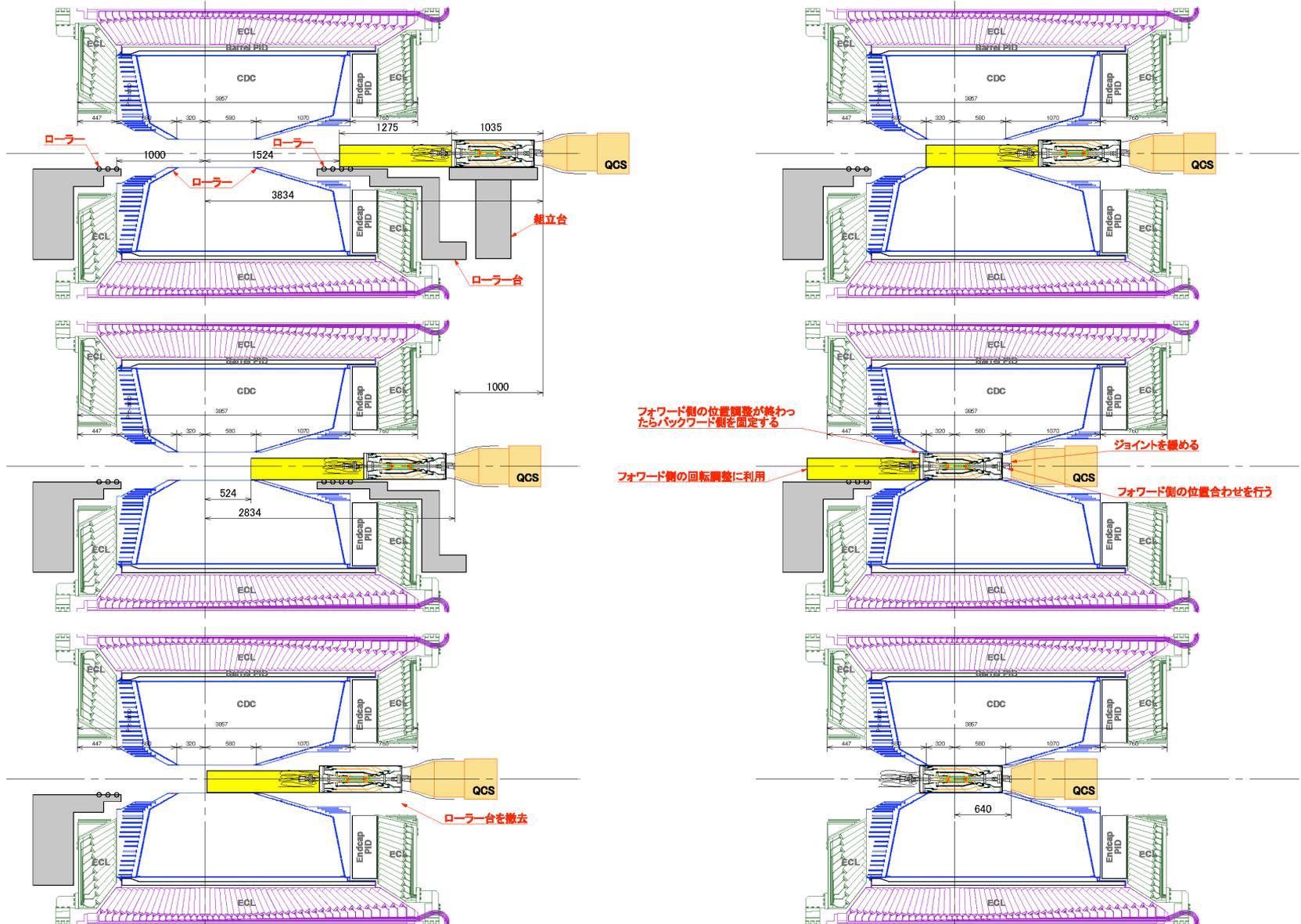
• Connection flanges for vacuum chambers.



Some work spaces to access flanges.
It will be possible to make use of these spaces.

Little work space to access flanges.
It is impossible to connect flanges by hands in this configuration.

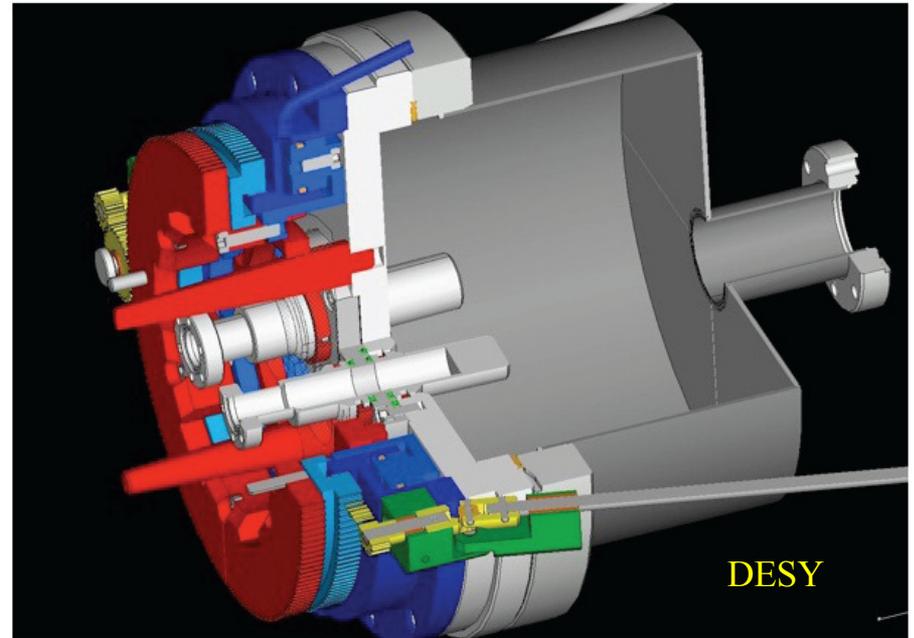
Installation Scenario - Baseline



Installation Scenario

Alternative Scenario with Remote vacuum seal mechanism.

- Some people feel uneasy on the situation that VXD unit is pushed by QCS in the baseline scenario.
- They proposed an alternative scenario to slide VXD with manual force and a remote vacuum seal mechanism.
- The mechanism is not yet valid with a mock-up test.
- However the choice of the installation scenario has various impacts on detailed designs of VXD and surrounding components.
- The decision on the choice cannot be delayed so long.



Vacuum around IR

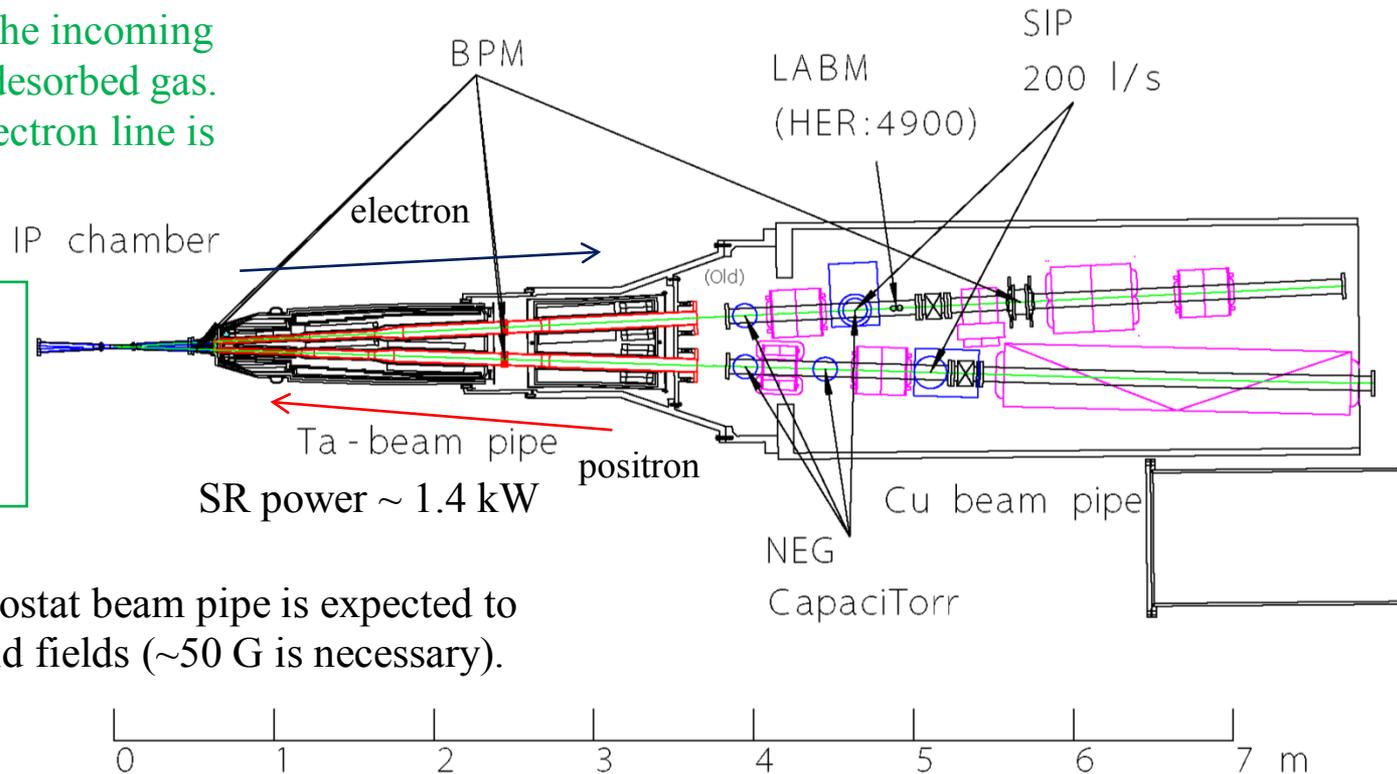
Layout of vacuum components near QCS in the R side

The beam pipe in the cryostat is made of **Ta** (red part in the figure). The maximum thickness of this pipe is 4 mm.

Pumps are located outside the cryostat.

The major gas load for the incoming positron line is photon-desorbed gas. That for the outgoing electron line is thermal outgassing.

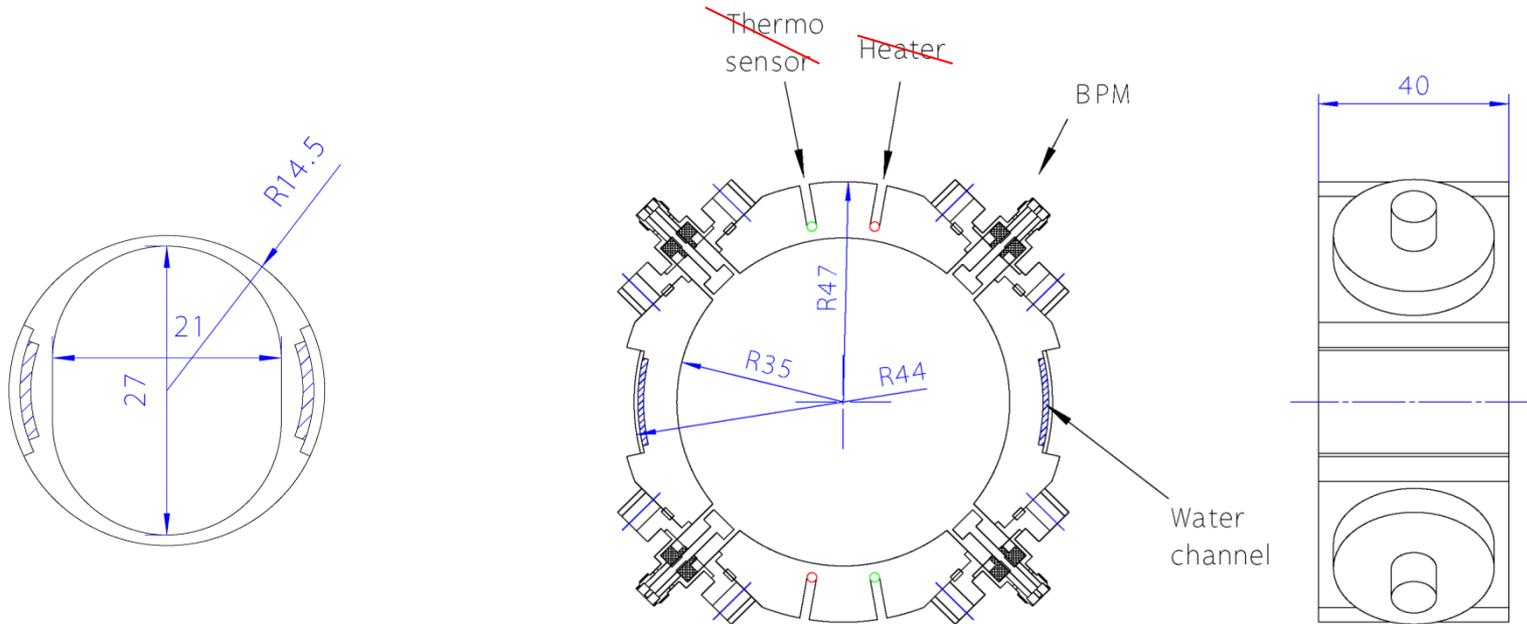
Ta beam pipes will be coated with Au or Cu to reduce ohmic power loss.



Electron cloud in the cryostat beam pipe is expected to be suppressed by solenoid fields (~50 G is necessary).

Vacuum around IR

Typical cross section of Ta beam pipe



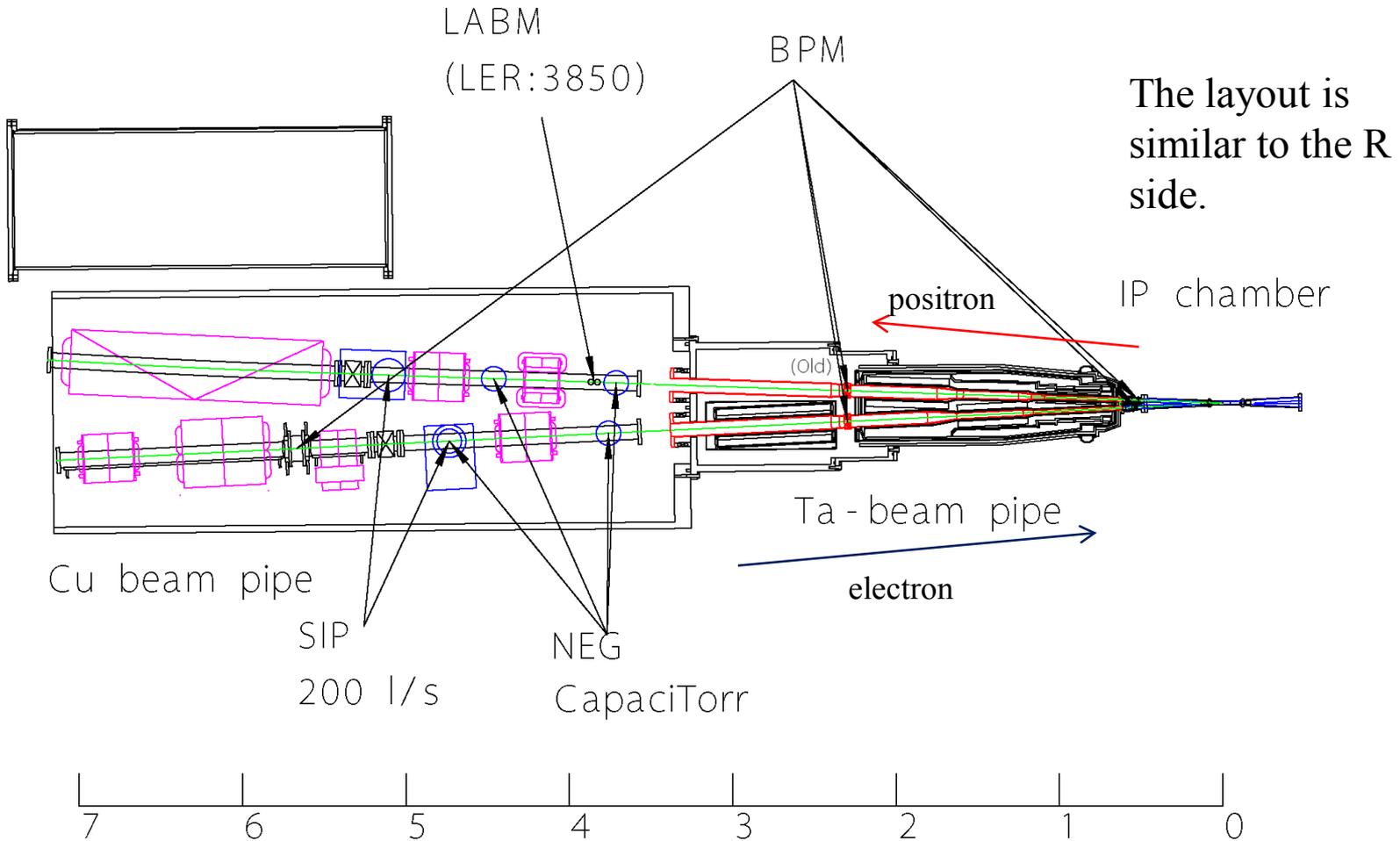
Vertically elongated aperture
in QC1P

(Larger aperture is preferable
but it is not available in the
present design.)

BPM

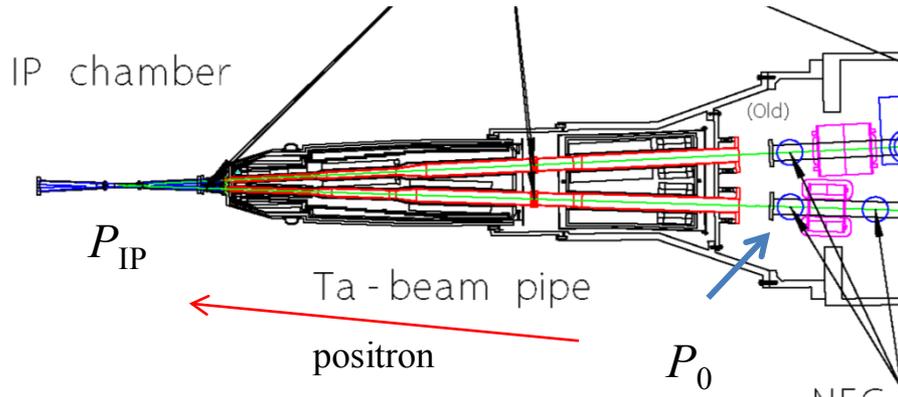
Vacuum around IR

Layout of vacuum components near QCS in the L side



Vacuum around IR

Rough estimation of pressure near IP



Thermal only

$$P_0 = 2 \times 10^{-7} \text{ Pa}$$

$$P_{IP} = 8 \times 10^{-7} \text{ Pa}$$

Photon - desorption dominant

$$P_0 = 2 \times \eta \text{ Pa}$$

$$P_{IP} = 11 \times \eta \text{ Pa}$$

η : photo - desorption coefficient

Example: Incoming positron line

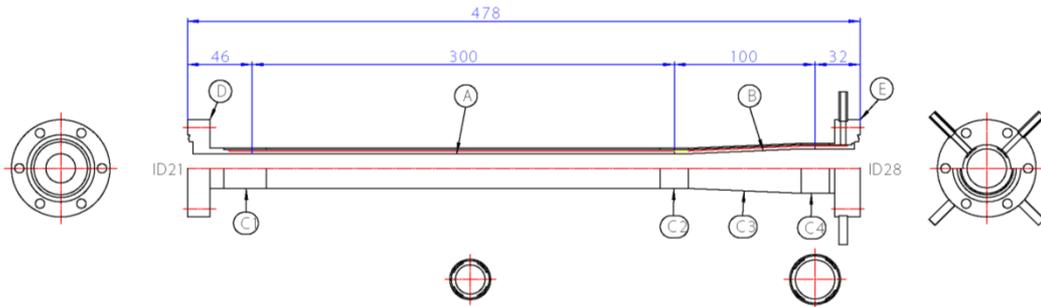
Assumptions:

- The equation for a long tube gives good estimation for a short tube
- At IP pressure is maximum
- P_0 is determined by the total outgassing of the cryostat beam pipe and the pumping speed there (50 l/s).
- The thermal outgassing rate is $1 \times 10^{-11} \text{ Torr}/\text{s}/\text{cm}^2$ ($1.33 \times 10^{-8} \text{ Pa m}^3/\text{s}/\text{m}^2$).

The difference between P_0 and P_{IP} is determined by the local outgassing and the conductance of the beam pipe. It doesn't depend on the pumping speed outside the cryostat.

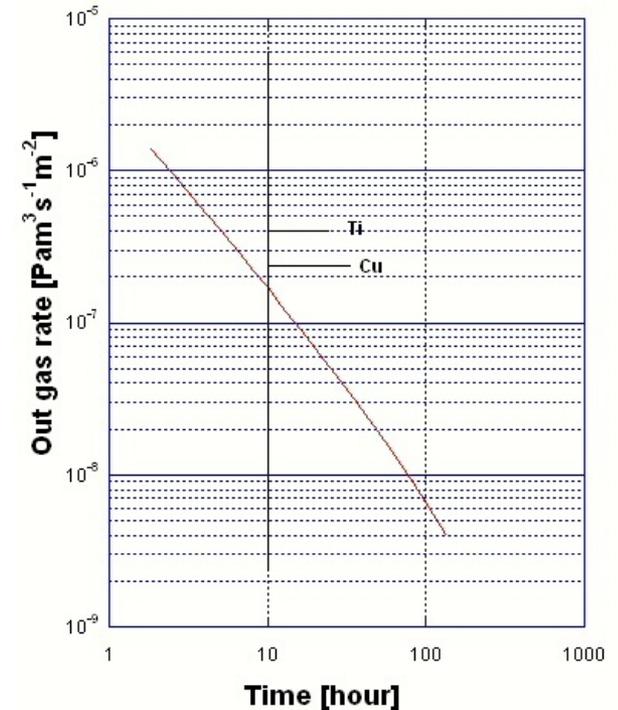
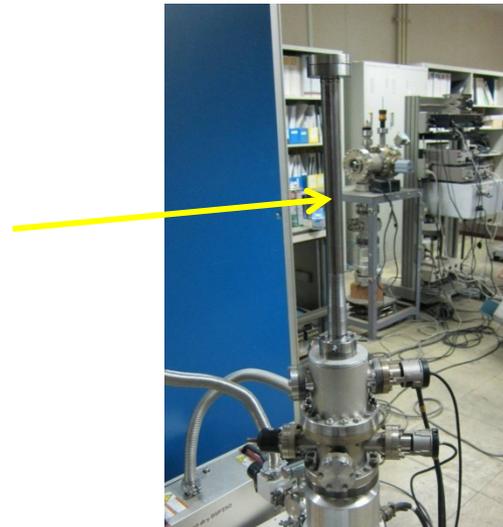
Vacuum around IR

Test Ta beam pipe



A test Ta beam pipe with cooling channels, a taper, and conflat flanges was fabricated.

Ta pipe model for QCS with cooling path in the wall. This pipe has a weld seam between water and vacuum. The test with tap water caused no leakage at least for months.



Thermal outgassing of the Ta pipe. **‘Very low’** (H. Hisamatsu)

Vacuum around IR

Photon-induced desorption of Ta, Au, and Cu (2nd)

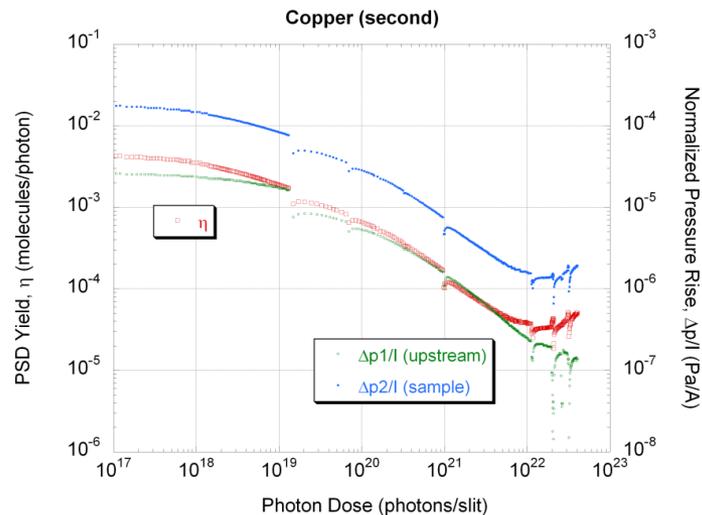
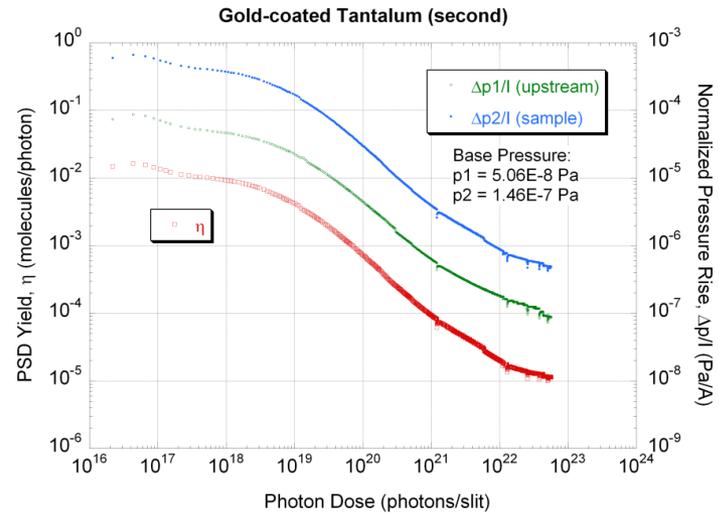
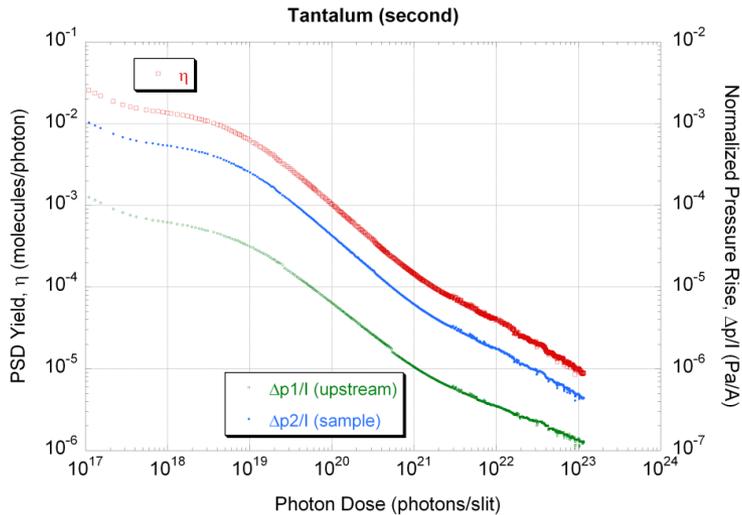


Photo-desorption coefficients of Cu, Ta, and Au-coated Ta. **Ta and Au-coating have a sufficiently low photo-desorption coefficient.**

(At PF BL21, $\epsilon_{cr} = 4$ keV, by Y. Tanimoto)

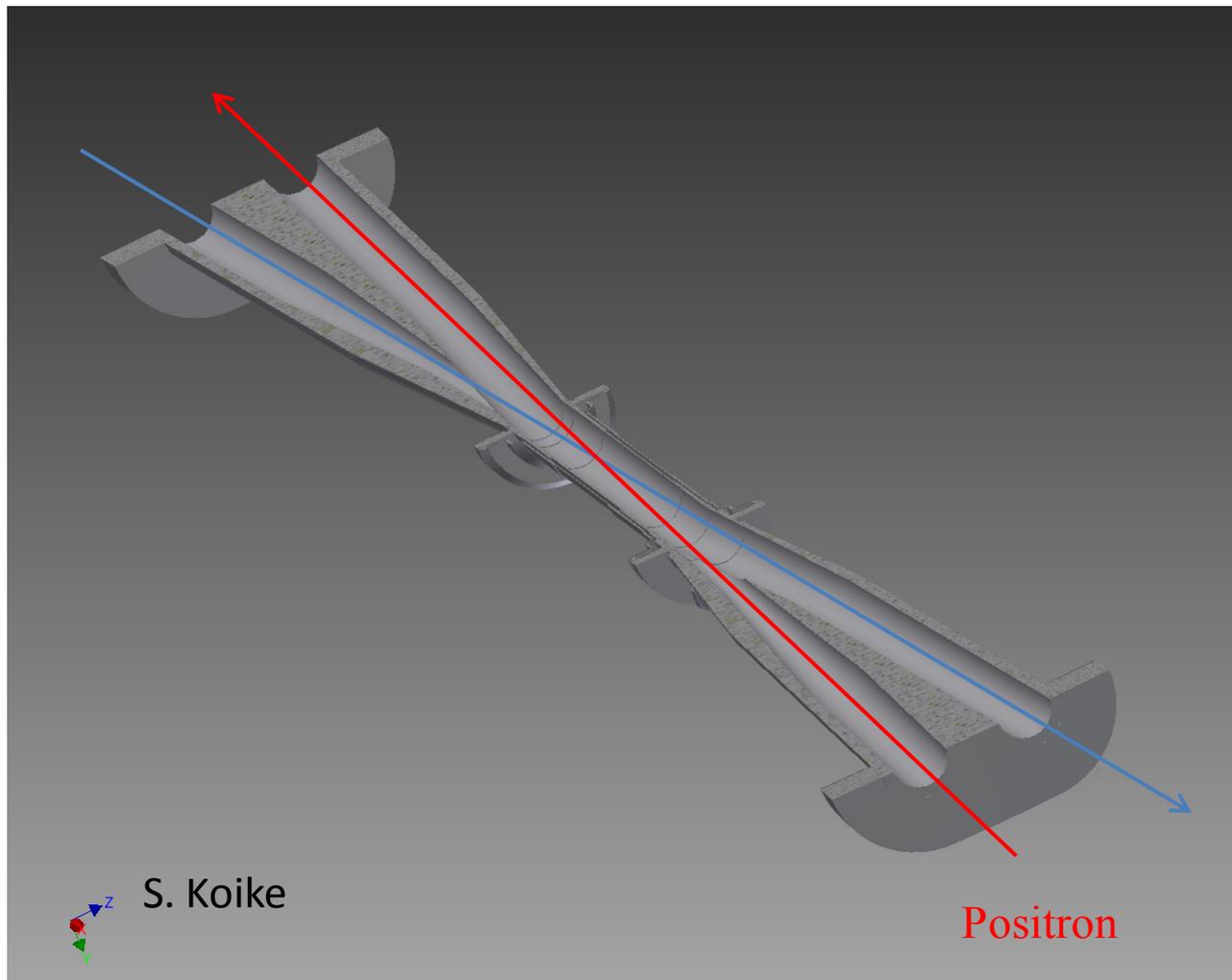
Vacuum around IR

Consideration on IR pressure

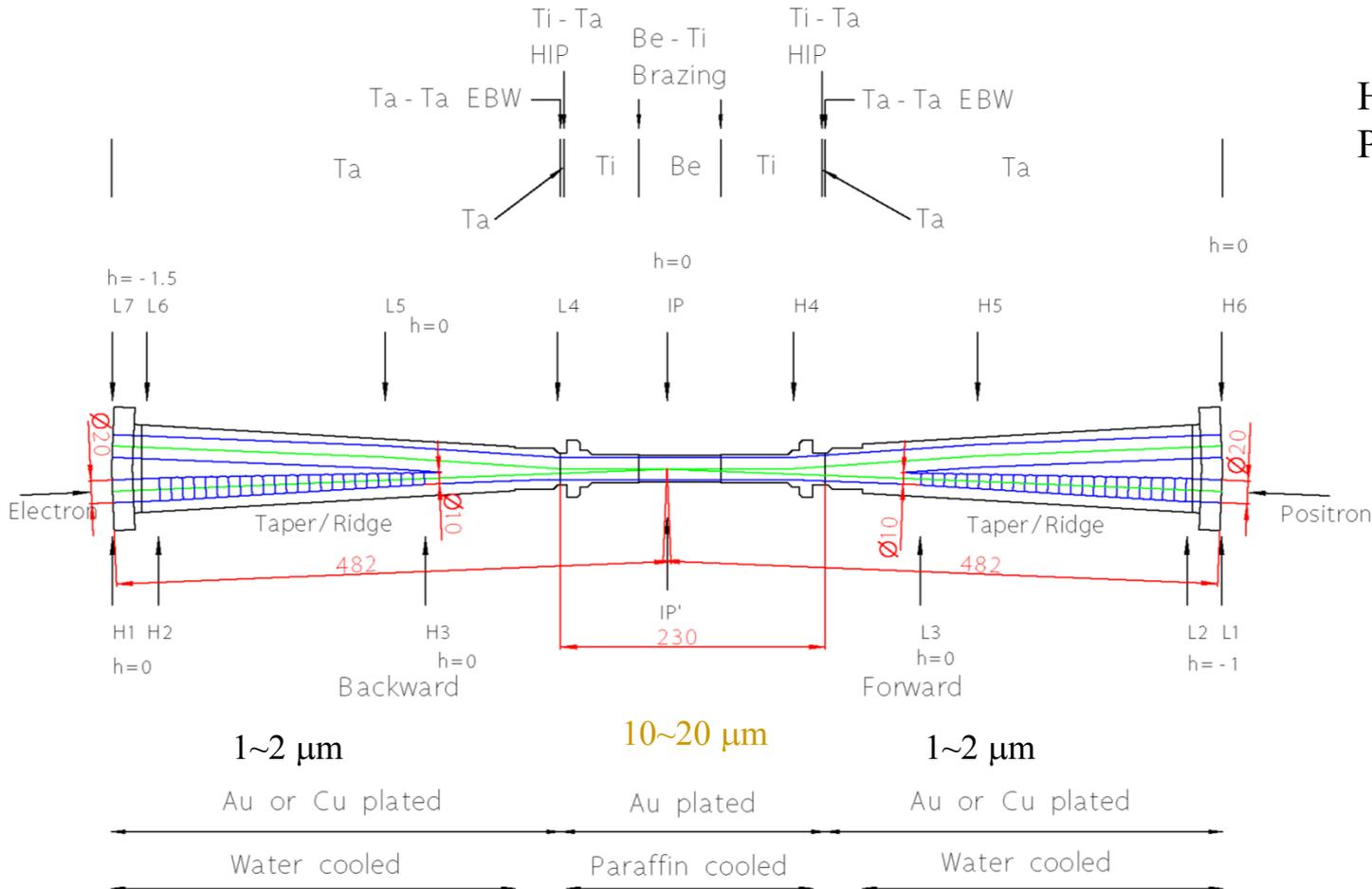
- At least, the pressure around the IP ($\pm 5\text{m}$) must not affect the overall average design pressure of the ring (1×10^{-7} Pa). **Therefore the target pressure in this region must be less than $1 \times 10^{-7} \times 3000/10 = 3 \times 10^{-5}$ Pa.** A consideration on the beam-gas Rutherford scattering requires much lower pressure in the QC magnets where β is large.
- The main gas source in this region is photon-desorbed gas due to the direct SR from the last bend. If a photo-desorption coefficient η is assumed to be 1×10^{-6} molecules/photon, The average pressure of this region will be a few $\times 10^{-6}$ Pa.
- It was shown that Ta and Au-coating have a sufficiently low photo-desorption coefficient. It was also shown Ta has a very low thermal outgassing rate.
- Still we are looking for an idea to improve IP pressure.

IP Chamber Cut View

Electron



IP Chamber Design feature



HIP = Hot Isostatic Pressing

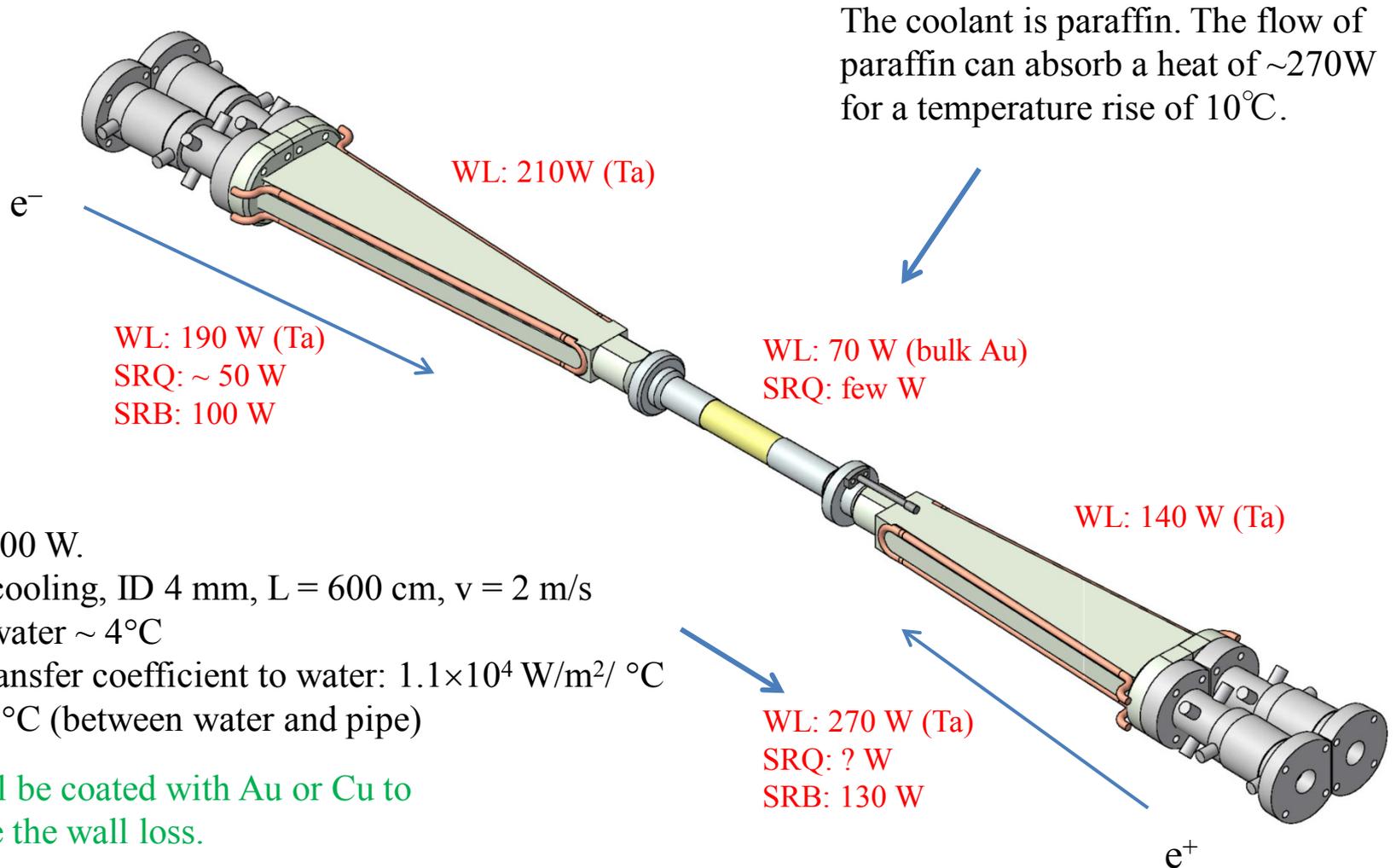
- The central straight part consists of double tube. Paraffin runs between them.
- The connection between double tubes is done by Ti-Ti EBW.

IP Chamber

R&D

- Done
 - Stress analysis
 - For the temperature difference between the two tubes at the center.
 - Changing support position of beam pipe
 - Fabrication test
 - Precise machining of Be pipes
 - NC machining of ridges
 - Be-Ti brazing
 - Ti-Ta HIP
 - EBW near by HIP
 - Pulsed sputter coating of Cu inside 2 cm Al pipe and its uniformity check
- To be done (in preparation)
 - Stress analysis
 - Check the strength under dynamic force
 - Fabrication test
 - Au coating on Ti pipe
 - Effect of EBW on the coating
 - Simulation welding between inner and outer Ti pipes
- Ta part will be fabricated in FY 2013 and the first version of IP chamber will appear within FY 2013

IP Chamber Cooling



Heat: 400 W.

Water cooling, ID 4 mm, $L = 600$ cm, $v = 2$ m/s

ΔT of water $\sim 4^\circ\text{C}$

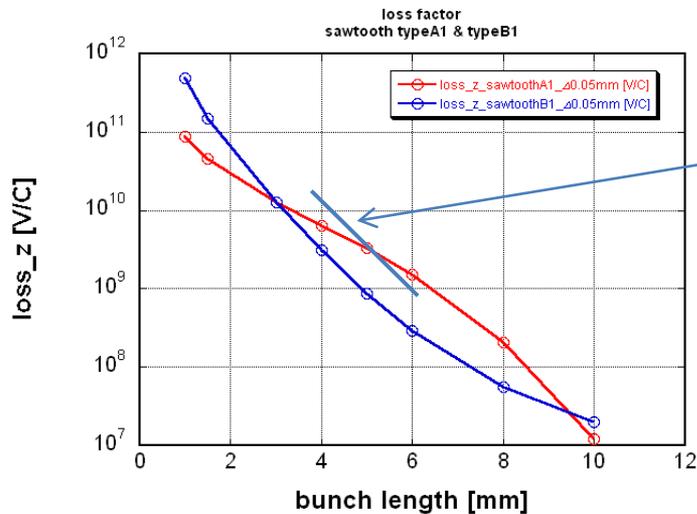
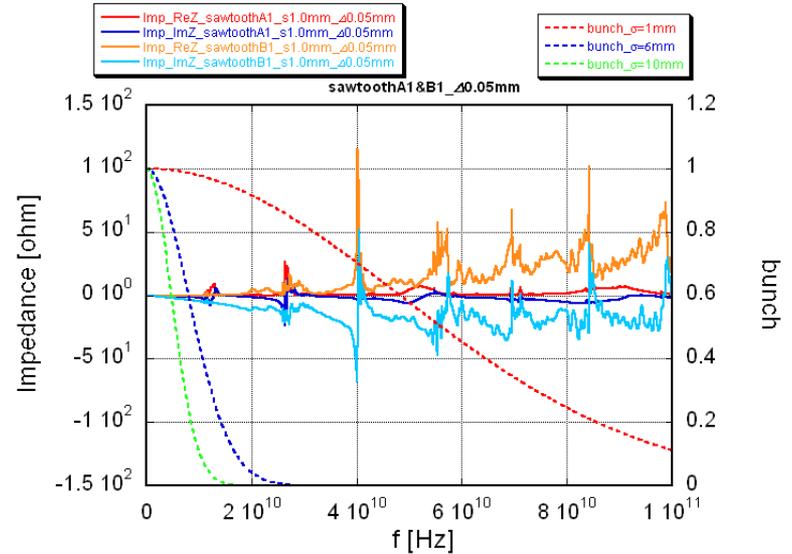
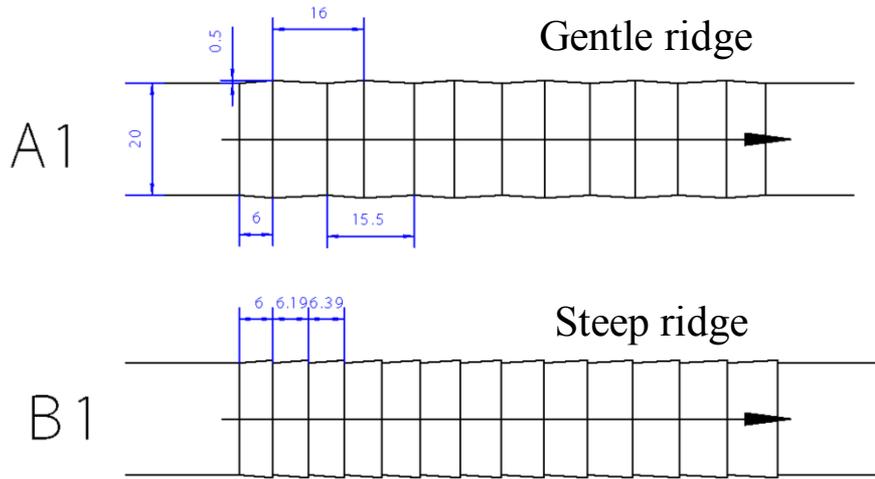
Heat transfer coefficient to water: 1.1×10^4 W/m²/ $^\circ\text{C}$

$\Delta T \sim 5$ $^\circ\text{C}$ (between water and pipe)

Ta will be coated with Au or Cu to reduce the wall loss.

IP Chamber

Are steep ridges permissible?



New ridge

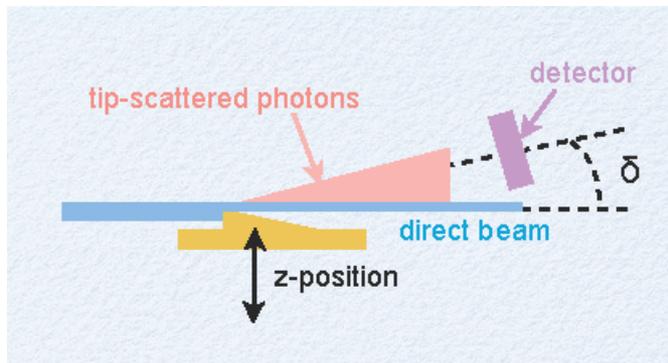
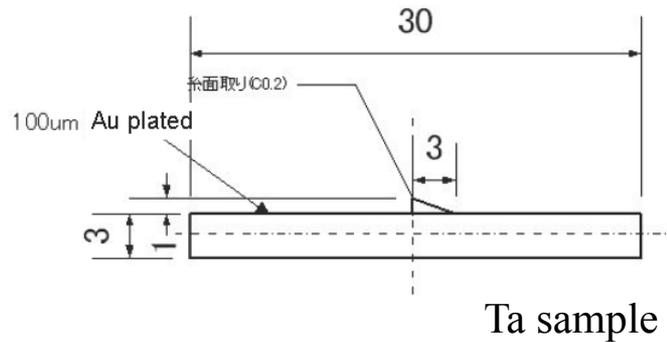
Since the height of the ridge is only 0.5 mm, structures of impedance due to the sharpness of ridges appears in higher frequencies than a 6mm bunch spectrum.

Steep ridges are OK.
(K. Shibata, Y.H. Chin)

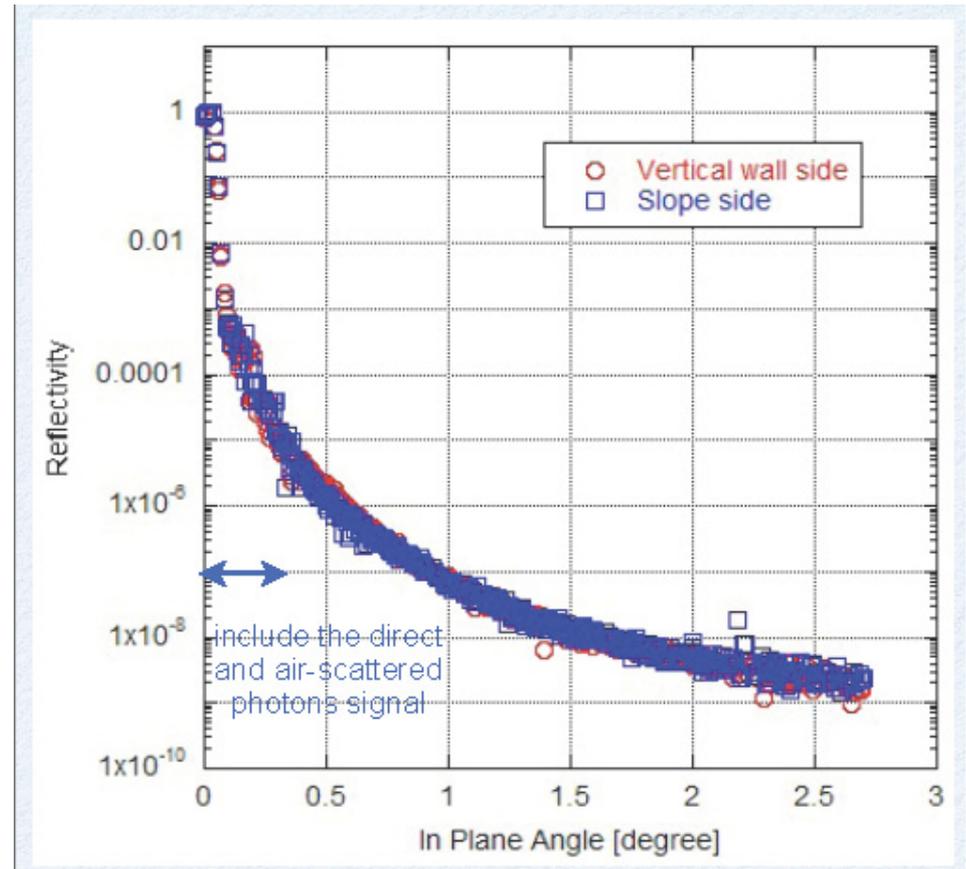
IP Chamber

Tip scattering on a ridge

T. Ishibashi, et al



Set up



CHESS (Cornell Univ.) G2 beam line

Photon energy : 9 keV

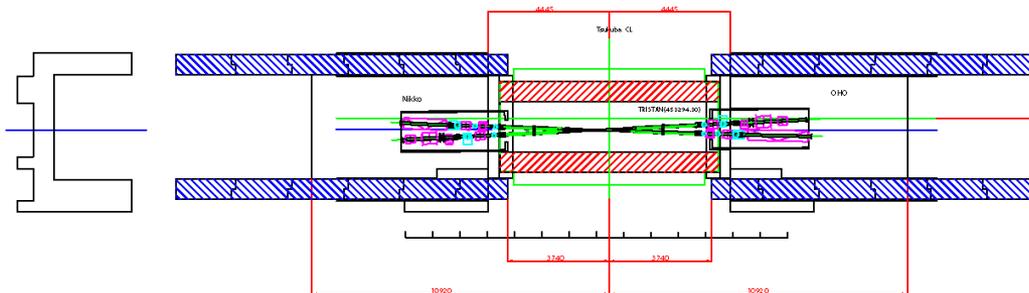
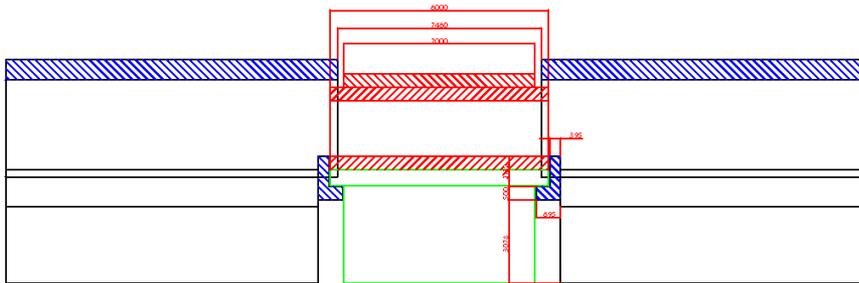
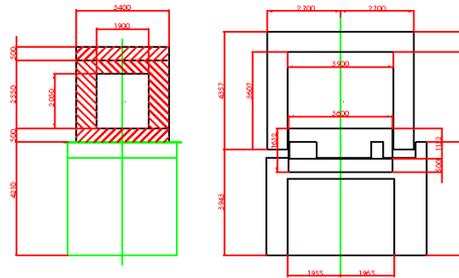
Slit : 2 mm (H) by 0.05 mm (V)

Detector angular resolution : 0.2 degree (FWHM)

Ratio of the scattered photon. The slope of the taper inside the pipe is 1.23 degree.

Radiation shield

Phase 1



Now on-going estimation of the beam loss at phase 1 suggests this structure is sufficient for Phase 1.
(Y. Ohnishi, T. Sanami)

Summary

- With the progress of the construction of SuperKEKB, the number of tasks to be solved for the interaction region is increasing.
- Among them,
 - We must make decision on the bridge reinforcement as soon as possible.
 - The choice of the installation scenario has various side effects. It cannot be delayed so long.
- And,
 - We are still looking for an idea to improve IP pressure.